

Title (en)

METHOD FOR SELECTIVELY ELECTROPLATING A STRIP-SHAPED, METAL SUPPORT MATERIAL

Title (de)

VERFAHREN ZUR SELEKTIVEN GALVANISIERUNG EINES BANDARTIGEN, METALLISCHEN TRÄGERMATERIALS

Title (fr)

PROCEDE POUR LA GALVANISATION SELECTIVE D'UN MATERIAU SUPPORT METALLIQUE EN FORME DE BANDE

Publication

**EP 1409772 B2 20080813 (DE)**

Application

**EP 02754718 A 20020620**

Priority

- DE 10135349 A 20010720
- EP 0206824 W 20020620

Abstract (en)

[origin: US6972082B2] A method for the continuous selective electroplating of a metallic substrate material ( 10 ) and more particularly of a substrate material band having prestamped contact elements, comprises the following steps: a) the substrate material ( 10 ) is coated in an electrophoretic coating means ( 14 ) with an electrophoretic coating composition selective with at least one composition strip, b) the at least one composition strip is removed at those parts by means of a laser ( 40 ), which are to be electroplated, c) in an electroplating process a metal layer is applied to the areas ( 42 ) deprived of composition in at least one composition strip using selective electroplating and d) the at least one composition strip is then removed.

IPC 8 full level

**C25D 5/02** (2006.01); **C25D 7/06** (2006.01); **C25D 13/22** (2006.01)

CPC (source: EP US)

**C25D 5/022** (2013.01 - EP US); **C25D 13/22** (2013.01 - EP US); **Y10S 205/917** (2013.01 - EP US)

Citation (opposition)

Opponent :

- DE 68910864 T2 19940601 - WHITAKER CORP [US]
- EP 0337658 A1 19891018 - AMP INC [US]
- EP 0106977 A2 19840502 - IBM [US]
- DD 246575 A1 19870610 - SEGHERS A MIKROELEKTRONIK VEB [DD]
- DE 69403926 T2 19980102 - MECO EQUIP ENG [NL]

Cited by

CN102888632A

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

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**US 2004206629 A1 20041021**; **US 6972082 B2 20051206**; AT E291110 T1 20050415; CN 1250777 C 20060412; CN 1533449 A 20040929; DE 10135349 A1 20030206; DE 50202493 D1 20050421; EP 1409772 A2 20040421; EP 1409772 B1 20050316; EP 1409772 B2 20080813; HK 1069607 A1 20050527; JP 2004536971 A 20041209; WO 03012175 A2 20030213; WO 03012175 A3 20031030

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